

CLAIMS

We claim:

Sub 502

1. A method of manufacturing a liquid crystal micro display (lcmd), said method comprising:
creating a hole in a substrate;
causing liquid crystal material to flow through said hole; and
sealing said hole.
2. The method of claim 1, further comprising :
testing said lcmd after sealing said hole.
3. The method of claim 2, further comprising:
separating said lcmd from other lcmds after testing said lcmd.
4. The method of claim 1, wherein said substrate is a semiconductor substrate.
5. The method of claim 4, wherein the semiconductor substrate comprises an integrated circuit.
6. The method of claim 4, wherein the semiconductor substrate is part of a silicon wafer.
7. The method of claim 1, wherein said substrate comprises glass.
8. The method of claim 1, wherein said hole is sealed using a sealant material selected from a group consisting of glue, epoxy, and solder.

Sub 10

Sub 15

Sub 20

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9. A method of manufacturing a first liquid crystal micro display (lcmd) comprising:
testing said first lcmd while it is physically connected to a second lcmd;
and
separating said first lcmd from said second lcmd after said testing.

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10. The method of claim 9, wherein said first lcmd comprises a semiconductor substrate having an integrated circuit and a glass substrate having a transparent electrode.

11. The method of claim 10, wherein said integrated circuit comprises electrodes.

12. The method of claim 11, wherein said testing includes causing a voltage difference between the integrated circuit electrodes and the transparent electrode.

13. The method of claim 12, wherein said testing includes determining whether the lcmd produces a uniform image.

14. A liquid crystal micro display (lcmd) comprising:
a first substrate; and
a second substrate having a hole extending through a thickness thereof.

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15. The lcmd of claim 14, wherein said hole can be used for filling the lcmd with liquid crystal material.

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16. The lcmd of claim 14, wherein the second substrate is a semiconductor substrate comprising an integrated circuit.

17. The lcmd of claim 14, wherein the second substrate comprises glass.

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18. The lcmd of claim 14, wherein said lcmd is physically connected to other lcmds.